

**APPENDIX A**  
**"CLEAN" VERSION OF EACH PARAGRAPH/SECTION/CLAIM**  
37 C.F.R. § 1.121(b)(ii) AND (c)(i)

**SPECIFICATION:**

Insertion at page 1, after line 1:

Cross-Reference to Related Applications:

a' This is a division of U.S. Patent Application Serial No. 09/627,021, filed July 27, 2000 in the name of Masanobu Okada and entitled SHIELDING CASE AND ELECTRONIC DEVICE HAVING SAME, now abandoned.

Replacement for paragraph at page 2, line 9:

a2 1004033-010302 After the shielding case 1 is mounted, there are cases where quality-control testing is performed to determine whether circuits on the circuit substrate 4 properly operate according to design specifications. As a result of the testing, if a circuit mounted on the circuit substrate 4 is not working sufficiently because of a defect found in an electronic component electromagnetically shielded in the shielding case 1, a component-replacement process or some other correction operation (which is referred to as reworking in the following) is performed. The reworking is performed such that the shielding case 1 is removed, and the defective electronic component is replaced with a new suitable component.

[Replacement for paragraph at page 2, line 22:]

In the reworking, the shielding case 1 is removed in the following steps. First, all solder joints fixing the leg sections 3 of the shielding case 1 are simultaneously heated and are melted. Then, in the state where all the solder joints are melted, the cover section 2 is lifted in the direction in which the cover section 2 will be separated from the circuit substrate 4. In this state, the individual leg sections 3 are pulled out through the through-holes 6 provided on the circuit substrate 4. In this way, the shielding case 1 can be removed from the circuit substrate 4.